

LVDS Interface ICs

4bit LVDS Driver



BU90LV047A

No.12057EAT02

●Description

LVDS Interface IC of ROHM "Serializer" "Deserializer" operate from 8MHz to 150MHz wide clock range, and number of bits range is from 35 to 70. Data is transmitted seven times (7X) stream and reduce cable number by 3(1/3) or less. The ROHM's LVDS has low swing mode to be able to expect further low EMI.

Driver and Receiver of 4 bits operate to 250MHz. It can be used for a variety of purposes, home appliances such as LCD-TV, business machines such as decoders, instruments, and medical equipment.

●Features

- 1) >500 Mbps (250 MHz) switching rates
- 2) Flow-through pinout simplifies PCB layout.
- 3) 300 ps typical differential skew
- 4) 400 ps maximum differential skew
- 5) 2.8 ns maximum propagation delay
- 6) 3.3V power supply design
- 7) $\pm 200\text{mV}$ and $\pm 350\text{mV}$ Selectable differential signaling
- 8) Interoperable with existing 5V LVDS receivers
- 9) High impedance on LVDS outputs on power down
- 10) Conforms to TIA/EIA-644 LVDS Standard
- 11) Industrial operating temperature range (-40°C to $+85^{\circ}\text{C}$)

●Applications

Car Navigation System
 Copier
 Digital TV (Signal System)
 FA equipment
 Medical equipment
 Vending machine, Ticket vending machine

●Precaution

- This chip is not designed to protect from radioactivity.
- This document may be used as strategic technical data which subjects to COCOM regulations.

●Block Diagram

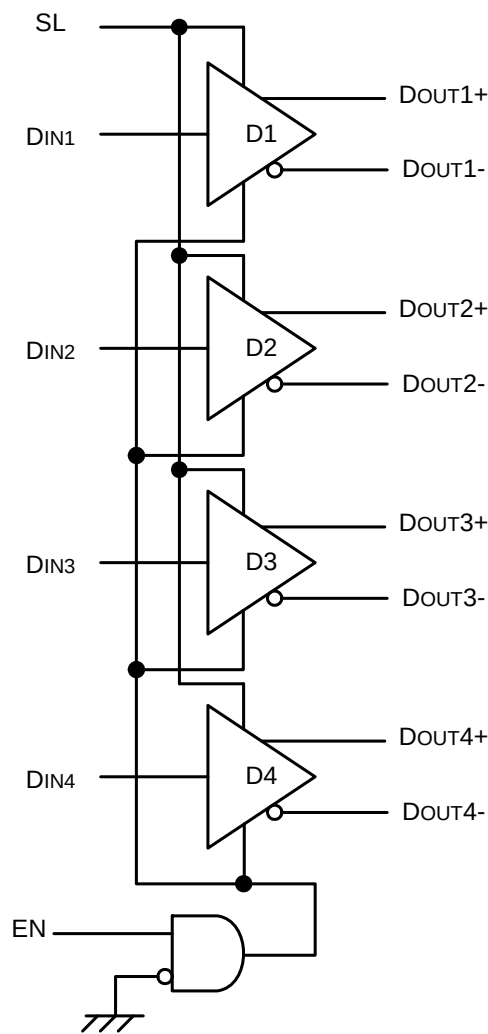


Fig.1. Block Diagram

●SSOP-B16 Package Outline and Specification

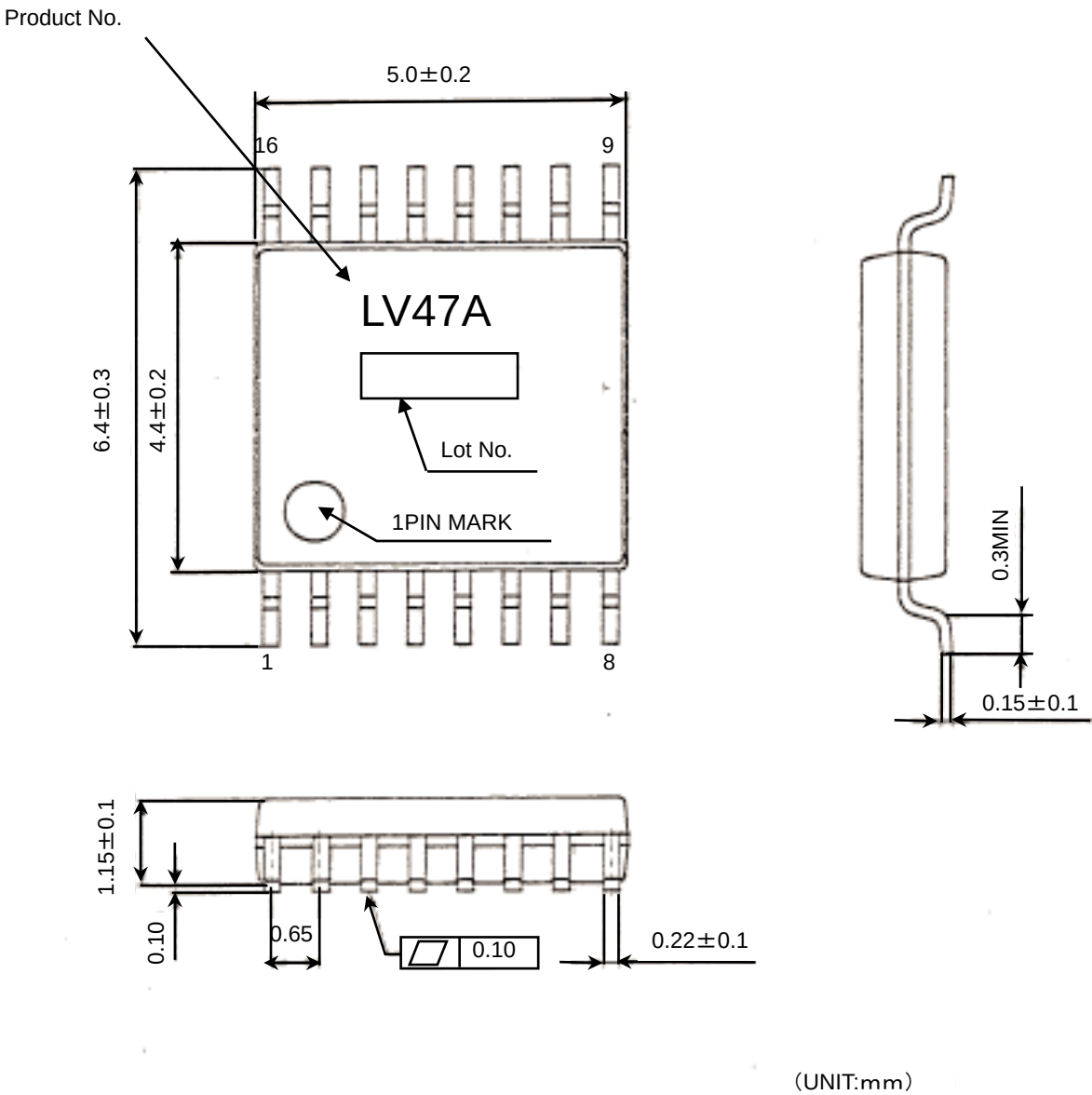


Fig.2. SSOP-B16 Package Outline and Specification

●Pin Configuration

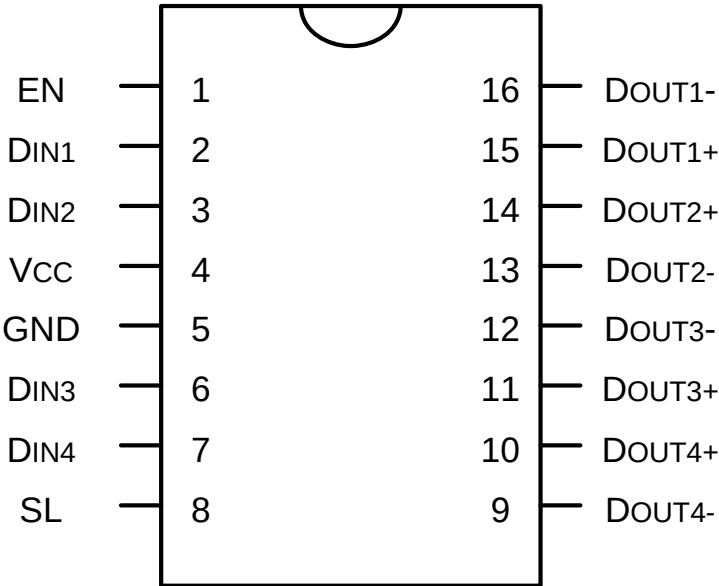


Fig.3. Pin Diagram (Top View)

●Pin Description

Table 1 : Pin Description

Pin Name	Pin No.	Type	Descriptions
DIN	2, 3, 6, 7	LVC MOS In	Driver input pin, LVC MOS compatible
DOUT+	10, 11, 14, 15	LVDS Out	Non-inverting driver output pin, LVDS levels
DOUT-	9, 12, 13, 16	LVDS Out	Inverting driver output pin, LVDS levels
SL	8	LVC MOS In	Swing Level select pin : When SL is high, the driver is reduce swing level (200mV). When SL is low or open, the driver is normal swing level (350mV).
EN	1	LVC MOS In	Driver enable pin: When EN is low or open, the driver is disabled. When EN is high, the driver is enabled.
VCC	4	Power	Power supply pin, $3.3V \pm 0.3V$
GND	5	GND	Ground pin

●Function Description

		INPUT	OUTPUTS		Swing Level
EN	SL	D _{IN}	D _{OUT} +	D _{OUT} -	
H	L or Open	L	L	H	350mV
		H	H	L	
H	H	L	L	H	200mV
		H	H	L	
All other combinations of EN, SL inputs		X	Z	Z	

●Absolute Maximum Ratings

Item	Symbol	Value		Unit
		Min.	Max.	
Supply voltage	VCC	-0.3	4.0	V
Input voltage	VIN	-0.3	VCC+0.3	V
Output voltage	VOOUT	-0.3	VCC+0.3	V
Storage temperature range	Tstg	-55	125	°C

●Package Power

Package	PD(mW)	DERATING(mW/°C) ※1
SSOP-B16	400	4.0
	450 ^{*2}	4.5 ^{※2}

※1 At temperature Ta > 25°C

※2 Package power when mounting on the PCB board.

The size of PCB board :70×70×1.6 (mm³)

The material of PCB board :The FR4 glass epoxy board.(3% or less copper foil area)

●Recommended Operating Conditions

Item	Symbol	Value			Unit	Condition
		Min.	Typ.	Max.		
Supply voltage	VCC	3.0	3.3	3.6	V	
Operating temperature range	Topr	-40	-	85	°C	

●DC Characteristics

Parameter	Symbol	Conditions	Pin	Min	Typ	Max	Units
Differential Output Voltage	V _{OD1}	SL= GND, R _L = 100 Ω (Fig.4)	D _{OUT-} D _{OUT+}	250	350	450	mV
Output High Voltage	V _{OH 1}			-	1.42	1.6	V
Output Low Voltage	V _{OL1}			0.90	1.08	-	V
Differential Output Voltage	V _{OD2}	SL= V _{CC} , R _L = 100 Ω (Fig.4)		120	200	300	mV
Output High Voltage	V _{OH2}			-	1.35	1.50	V
Output Low Voltage	V _{OL2}			1.00	1.15	-	V
Change in Magnitude of V _{OD} for Complementary Output States	ΔV _{OD}	SL = V _{CC} or GND, R _L = 100 Ω (Fig.4)		-	1	35	mV
Offset Voltage	V _{OS}			1.125	1.25	1.375	V
Change in Magnitude of Vos for Complementary Output States	ΔV _{OS}			-	1	25	mV
Input High Voltage	V _{IH}		D _{IN} ,	V _{CC} × 0.8	-	V _{CC}	V
Input Low Voltage	V _{IL}		SL	GND	-	V _{CC} × 0.2	V
Input Current	I _I	V _{IN} = 0V or V _{CC} , Other Input = V _{CC} or GND	EN	-10	-	+10	μ A
Input Clamp Voltage	V _{CL}	I _{CL} = -18mA		-1.5	-0.8	-	V
Output Short Circuit Current	I _{OS}	ENABLED, D _{IN} = V _{CC} , D _{OUT+} = 0V or D _{IN} = GND, D _{OUT-} = 0V	D _{OUT-} D _{OUT+}	-	-5.4	-9.0	mA
Differential Output Short Circuit Current	I _{OSD}	ENABLED, V _{OD} = 0V		-	-5.4	-9.0	mA
Power-off Leakage	I _{OFF}	V _{OUT} = 0V or 3.6V, V _{CC} =0V or Open		-20	±1	+20	μ A
No Load Supply Current Drivers Enabled	I _{CC}	D _{IN} = V _{CC} or GND	V _{CC}	-	20	-	mA
Load Supply Current Drivers Enabled	I _{CCCL}	R _L = 100 Ω All Channels, D _{IN} = V _{CC} or GND (all outputs)		-	20	-	mA
No Load Supply Current Drivers Disabled	I _{CCZ}	D _{IN} = V _{CC} or GND, EN = GND, SL = GND		-	3	-	mA

●Switching Characteristics

$V_{CC} = +3.3V \pm 0.3V$, $T_{opr} = -40^{\circ}C$ to $+85^{\circ}C$

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Differential Propagation Delay High to Low	t_{PHLD}	$R_L = 100\Omega$, $C_L = 15pF$ (Fig.5 and Fig.6)	0.5	1.7	2.8	ns
Differential Propagation Delay Low to High	t_{PLHD}		0.5	1.7	2.8	ns
Differential Pulse Skew $ t_{PHLD} - t_{PLHD} $	t_{SKD1}		0	0.3	0.4	ns
Channel-to-Channel Skew	t_{SKD2}		0	0.4	0.5	ns
Differential Part to Part Skew	t_{SKD3}		0	-	1.0	ns
Differential Part to Part Skew	t_{SKD4}		0	-	1.2	ns
Rise Time	t_{TLH}		-	0.5	1.5	ns
Fall Time	t_{THL}		-	0.5	1.5	ns
Disable Time High to Z	t_{PHZ}	$R_L = 100\Omega$, $C_L = 15pF$ (Fig.7 and Fig.8)	-	2	5	ns
Disable Time Low to Z	t_{PLZ}		-	2	5	ns
Enable Time Z to High	t_{PZH}		-	3	7	ns
Enable Time Z to Low	t_{PZL}		-	3	7	ns
Maximum Operating Frequency	f_{Max}		250	-	-	MHz

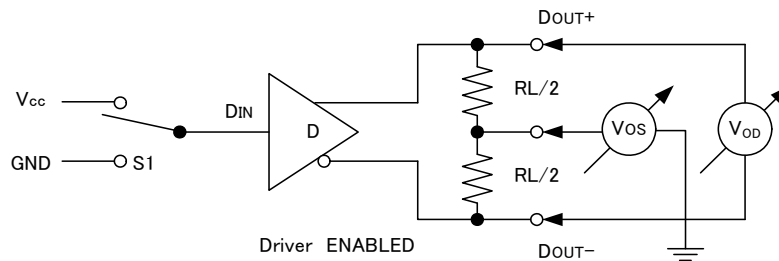


Fig.4. Driver VOD and VOS Test Circuit

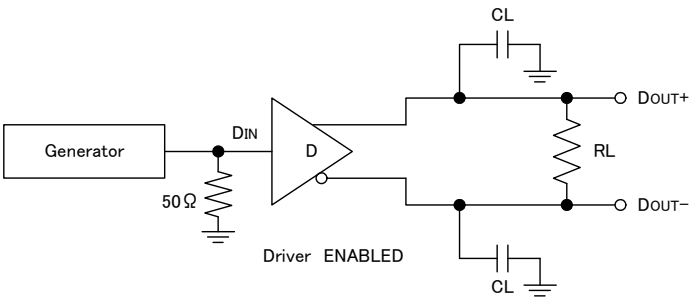


Fig.5. Driver Propagation Delay and Transition Time Test Circuit

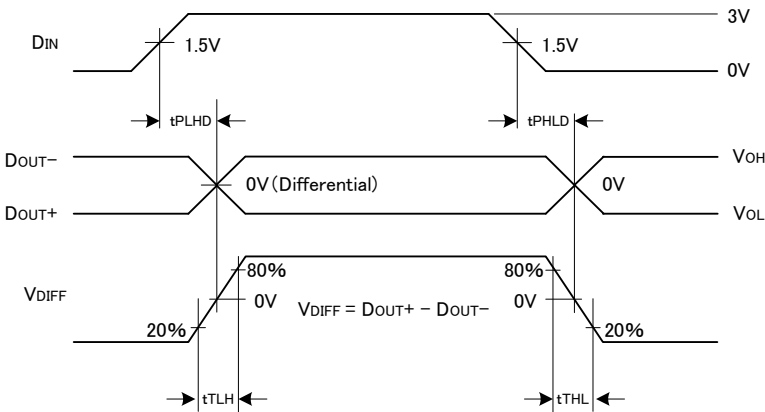


Fig.6. Driver Propagation Delay and Transition Time Waveforms

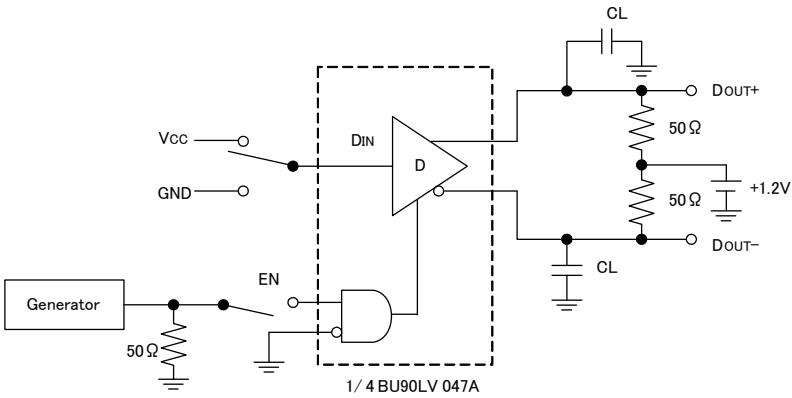


Fig.7. Driver 3-STATE Delay Test Circuit

Parameter Measurement Information (Continued)

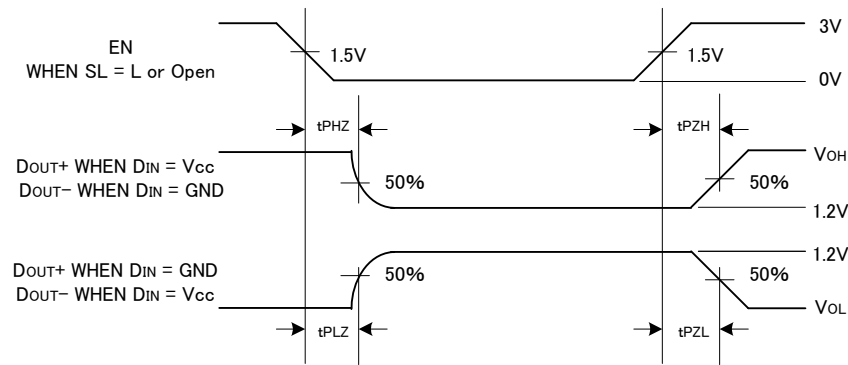


Fig.8. Driver 3-STATE Delay Waveform

Typical Application

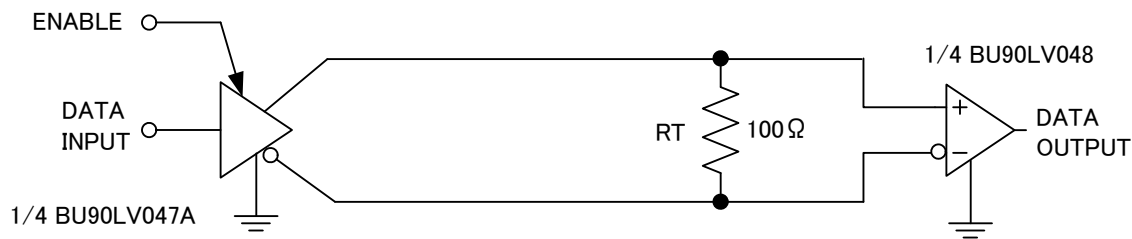


Fig.9. Point-to-Point Application

Typical Application (Continued)

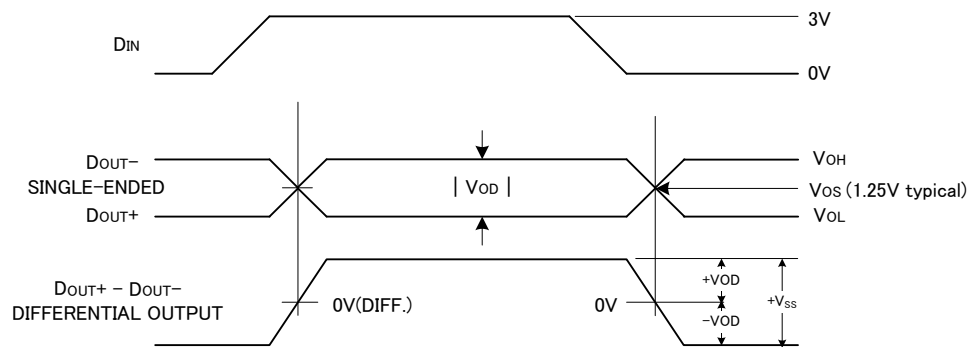


Fig.10. Driver Output Levels

●Ordering part number

B	U	9	0	L	V	0	4	7	A	-	E	2
Part No.		Part No. 90LV047A (Package: SSOP-B16)								Packaging and forming specification E2: Embossed tape and reel		

SSOP-B16

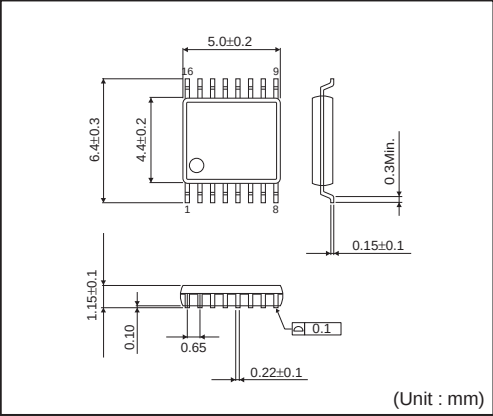


Diagram showing the dimensions of the SSOP-B16 package. The package is a 16-pin Small Outline Package (SSOP). Dimensions are given in millimeters (mm). The package width is 5.0±0.2 mm. The package height is 6.4±0.3 mm. The pin pitch is 0.65 mm. The pin width is 0.15±0.1 mm. The pin length is 0.3mm. The package thickness is 0.22±0.1 mm. The package is shown in a side view and a top view. The top view shows the package is 5.0±0.2 mm wide and 6.4±0.3 mm high. The side view shows the package is 0.22±0.1 mm thick. The pin pitch is 0.65 mm. The pin width is 0.15±0.1 mm. The pin length is 0.3mm. The package is shown in a side view and a top view. The top view shows the package is 5.0±0.2 mm wide and 6.4±0.3 mm high. The side view shows the package is 0.22±0.1 mm thick. The pin pitch is 0.65 mm. The pin width is 0.15±0.1 mm. The pin length is 0.3mm. (Unit : mm)

<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)

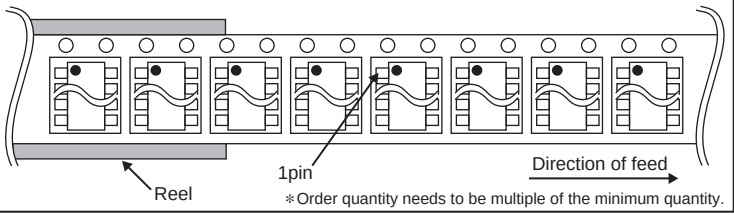


Diagram showing the tape and reel information. The diagram shows a carrier tape with 16 pins. The pins are numbered 1 to 16. The direction of feed is indicated by an arrow pointing to the right. The reel is indicated by an arrow pointing to the left. The diagram shows the carrier tape is 5.0±0.2 mm wide. The pin pitch is 0.65 mm. The pin width is 0.15±0.1 mm. The pin length is 0.3mm. The package thickness is 0.22±0.1 mm. The package is shown in a side view and a top view. The top view shows the package is 5.0±0.2 mm wide and 6.4±0.3 mm high. The side view shows the package is 0.22±0.1 mm thick. The pin pitch is 0.65 mm. The pin width is 0.15±0.1 mm. The pin length is 0.3mm. The package is shown in a side view and a top view. The top view shows the package is 5.0±0.2 mm wide and 6.4±0.3 mm high. The side view shows the package is 0.22±0.1 mm thick. The pin pitch is 0.65 mm. The pin width is 0.15±0.1 mm. The pin length is 0.3mm. 1pin
* Order quantity needs to be multiple of the minimum quantity.

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

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1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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